

Revisiting MCBHCB Requirements in Support of 50G/lane PAM4

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Comment 128 was submitted on P802.3bs draft 1.4 that mated board of CL92 crosstalk is excessive in support of 50G Cu cabling

- Comment was rejected as P802.3bs does not define Cu cabling
- After further investigation P802.3bs C2M simulation were all based on channels having < ¼ the amount of crosstalk in CL92
- Mated board crosstalk of CL92 need to reduced for 50G PAM4 C2M and Cu cabling applications

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50G Mated Board References Legacy CL92 MCB/HCB Specifications



Currently CL 120E.4.1 MCB/HCB specifications references

- CL 92.11.1 for HCB specifications
- CL 92.11.2 for the MCB specifications
- CL 92.11.3.6 defines mated text fixture ICN
 - MDFEXT of 4.8 mV is excessive for 50G PAM4 link!

Table 92–13—Mated test fixtures integrated crosstalk noise

Parameter	100GBASE-CR4	Units	
MDNEXT integrated crosstalk noise voltage	Less than 1.8	mV	
MDFEXT integrated crosstalk noise voltage	Less than 4.8	mV	

Bases for the Mated MCB/HCB MDFEXT/MDNEXT in CL92



Vintage QSFP+ connector provided bases for the CL92 MDFEXT and MDNEXT

<u>http://www.ieee802.org/3/bj/public/sep12/ghiasi_3bj_01a_0912.pdf</u>

MCB-HCB Crosstalk	10.3125 GBd ICN (mV)	25.78 GBd ICN (mV)	28.0 GBd ICN (mV)
Rise Time 20-80% (ps)	24.000	9.600	8.840
MDNEXT	0.323	1.390	1.612
MDFEXT	3.593	4.562	4.673
ICN	3.607	4.769	4.943



802.3bs C2M Base Analysis Used Channels with Significantly Lower NEXT/FEXT



CDAUI-8/CCAUI-4 base channels

http://www.ieee802.org/3/bs/public/adhoc/elect/24Aug_15/dallaire_01_082415_elect.pdf _

CHANNEL	FEXT	NEXT	IL @ 13.28125 GHz (dB)	ILD (dBrms)
From IEEE 802.3bs shanbhag_3bs_14_0623:				
(1) Nelco 4000-13SI Host PCB + next gen 28Gb/s high density SMT IO	5	0	8.7	0.110
(2) EM-888 Host PCB + next gen 28Gb/s press-fit stacked IO	7	0	8.9	0.051
From IEEE 802.3bs shanbhag_3bs_01_1014:				
(3) 4in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO	5	0	4.3	0.110
(4) 10in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO	5	0	8.8	0.106
(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO	7	0	4.5	0.051
(6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO	7	0	9.0	0.052
Cisco Channels:				
(7) Cisco 2in Stacked	0	0	8.5	0.237
(8) Cisco 5in Stacked	0	0	11.3	0.245
	CHANNEL From IEEE 802.3bs shanbhag_3bs_14_0623: (1) Nelco 4000-13SI Host PCB + next gen 28Gb/s high density SMT IO (2) EM-888 Host PCB + next gen 28Gb/s press-fit stacked IO From IEEE 802.3bs shanbhag_3bs_01_1014: (3) 4in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO (4) 10in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO (5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO (7) Cisco 2in Stacked (8) Cisco 5in Stacked (7) Cisco 5in Stacked [8] Cisco 5in Stacked	CHANNELFEXTFrom IEEE 802.3bs shanbhag_3bs_14_0623:(1) Nelco 4000-13SI Host PCB + next gen 28Gb/s high density SMT IO5(2) EM-888 Host PCB + next gen 28Gb/s press-fit stacked IO7From IEEE 802.3bs shanbhag_3bs_01_1014:5(3) 4in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO5(4) 10in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO5(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO7(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO7(5) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO7(6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO7(7) Cisco 2in Stacked0(8) Cisco 5in Stacked0	CHANNELFEXTNEXTFrom IEEE 802.3bs shanbhag_3bs_14_0623:50(1) Nelco 4000-13SI Host PCB + next gen 28Gb/s high density SMT IO50(2) EM-888 Host PCB + next gen 28Gb/s press-fit stacked IO70From IEEE 802.3bs shanbhag_3bs_01_1014:50(3) 4in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO50(4) 10in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO50(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO70(6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO70(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO70(5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO70(5) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO70(7) Cisco 2in Stacked000(8) Cisco 5in Stacked000	CHANNEL FEXT NEXT IL @ 13.28125 GHz (dB) From IEEE 802.3bs shanbhag_3bs_14_0623: 5 0 8.7 (1) Nelco 4000-13SI Host PCB + next gen 28Gb/s high density SMT IO 5 0 8.7 (2) EM-888 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 8.9 From IEEE 802.3bs shanbhag_3bs_01_014: 5 0 4.3 (3) 4in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO 5 0 4.3 (4) 10in Megtron6 Host PCB + next gen 28Gb/s high density SMT IO 5 0 8.8 (5) 4in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 4.5 (5) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 9.0 (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 9.0 (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 9.0 (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 7 0 9.0 (6) 10in Megtron6 Host PCB + next gen 28Gb/s press-fit stacked IO 0 0 8.5 (7) Cisco 2in Stacked

Crosstalk for C2M Test Case 3 and 5



Mated board had no NEXT and with excellent FEXT

- <u>http://www.ieee802.org/3/bs/public/channel/TEC/shanbhag_3bs_01_1014.pdf</u>
- The C2M analysis in P802.3bs are based on channels with 5-7x lower crosstalk than mated board referenced currently!



Cable Under Consideration for 3 m Objective

- 000000 **Cable under consideration as tested meet the 3 m objective with** excellent ICN and PSXT
 - http://www.ieee802.org/3/50G/public/Mar16/ghiasi 50GE NGOATH 01a 0316.pdf _
 - To set the limit on mated board crosstalk the cable text board (MCB) should be _ measured with a well constructed HCB
 - PSXT result below are damped by the host channel. —

Test Cases	Cable IL (dB)	Channel IL (dB)	ISI/Noise/ XTALK	ILD	ICN (mV)	PSXT (mV)	COM (dB)
zQSFP T3-R3 3 m 26 AWG (Leoni Cable) 12 mm PKG	16.4	29.4	23/65/12%	0.26	1.09	1.30	4.82
zQSFP T3-R3 3 m 26 AWG (Leoni Cable) 30 mm PKG	16.4	29.4	20/70/10%	0.26	0.79	1.02	4.26
zQSFP T4-R4 3 m 26 AWG (Leoni Cable) 12 mm PKG	16.6	29.5	27/64/9	0.23	1.09	1.27	4.97
zQSFP T4-R4 3 m 26 AWG (Leoni Cable) 30 mm PKG	16.6	29.5	22/69/9	0.23	1.09	0.99	4.39
zQSFP T3-R3 3 m 26 AWG (Newer Cable P1) 12 mm PKG	14.3	27.3	24/69/6%	0.13	0.79	1.03	5.87
zQSFP T3-R3 3 m 26 AWG (Newer Cable P1) 30 mm PKG	14.3	27.3	24/71/5%	0.13	0.79	0.83	5.29
zQSFP T4-R4 3 m 26 AWG (Newer Cable P2) 12 mm PKG	14.4	27.3	19/75/6%	0.10	0.66	0.89	6.00
zQSFP T4-R4 3 m 26 AWG (Newer Cable P2) 30 mm PKG	14.4	27.3	24/72/4%	0.10	0.66	0.72	5.40
zQSFP T3-R3 3 m 26 AWG (Newer Cable P1) 12 mm PKG zQSFP T3-R3 3 m 26 AWG (Newer Cable P1) 30 mm PKG zQSFP T4-R4 3 m 26 AWG (Newer Cable P2) 12 mm PKG zQSFP T4-R4 3 m 26 AWG (Newer Cable P2) 30 mm PKG	14.3 14.3 14.4 14.4	27.3 27.3 27.3 27.3 27.3	24/69/6% 24/71/5% 19/75/6% 24/72/4%	0.13 0.13 0.10 0.10	0.79 0.79 0.66 0.66	1.03 0.83 0.89 0.72	5.87 5.29 6.00 5.40

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Crosstalk for Newer Molex 2 m and 3 m Cable



- MDFEXT and MDNEXT for cable assembly includes two connectors isolated by cable attenuation and is not directly representative of mated board crosstalk
 - http://www.ieee802.org/3/50G/public/Jan16/roth 50GE NGOATH 01a 0116.pdf
 - The 3 m cable meets the objective with excellent COM margin, measuring the matted _ crosstalk on the MCB cable tested can provide direct crosstalk!



Other MCB/HCB Parameters that Need Touch Up



Best to create updated clause for inclusion into 802.3bs or cd draft

- MCB frequency response Fig 92-16 need to be extended to 26.55 GHz
- Mated test board frequency response Fig 92-19 need to be extended to 26.55 GHz
- Mated test board return loss Fig 92-20 need to be extended to 26.55
 GHz
- Mated board common mode conversion loss 92-21 need to be extended to 26.55 GHz
- Mated board common mode return loss 92-22 need to be extended to 26.55 GHz
- Mated board common mode to differential return loss 92-23 need to be extended to 26.55 GHz

CL 92 limits preferably should be scaled to have the same value at 26.55 GHz.

Summary



- CL92 mated board MDFEXT (4.8 mV) and MDNEXT (1.8 mV) too high for 50G/lane PAM4 C2M or Cu cabling applications
- All of the mated board frequency response need to extend to new PAM4 Baudrate of 26.55 GHz, slight change
- However the MDNEXT and MDFEXT limits of CL 92 for mated MCB/HCB maybe too high to support 50G PAM4 operation
 - The Molex 3 m 26 AWG cable data show excellent proof of feasibility supporting the 3m objective
 - Additional measurement is needed to more accurately set MCB/HCB limits
 - Baseline simulation of 802.3bs C2M simulation had no NEXT and with optimistic MDFEXT level that might be difficult to meet with QSFP56 connector
- May want to consider new clause to define mated MCB/HCB instead of referencing CL92
 - Based on limited data available the MCB/HCB crosstalk should be ~ halved from limits of CL92.